DATA BOOK
PACKAGE OUTLINE

SUBSTRATE EXAMPLE
4041137

DRAFTER:	ANIS FAUZI	DATE:	07/10/2025
DESIGNER:		DATE:	
CHECKER:	K. SINCERBOX	DATE:	07/10/2025
ENGINEER:	LI JIANG	DATE:	07/10/2025
APPROVED:	NICK CHU	DATE:	07/10/2025
RELEASED:	ANIS FAUZI	DATE:	07/10/2025
TEMPLATE INFO:	EDGE# 4218519	DATE:	03/20/2013

DIMENSIONS IN MILLIMETERS

TEXAS INSTRUMENTS
SEMICONDUCTOR OPERATIONS

CODE IDENTITY NUMBER
01295

ePOD, HFG0084B / CFP,
84 PIN, 0.635 MM PITCH

SCALE	SIZE		REV	PAGE
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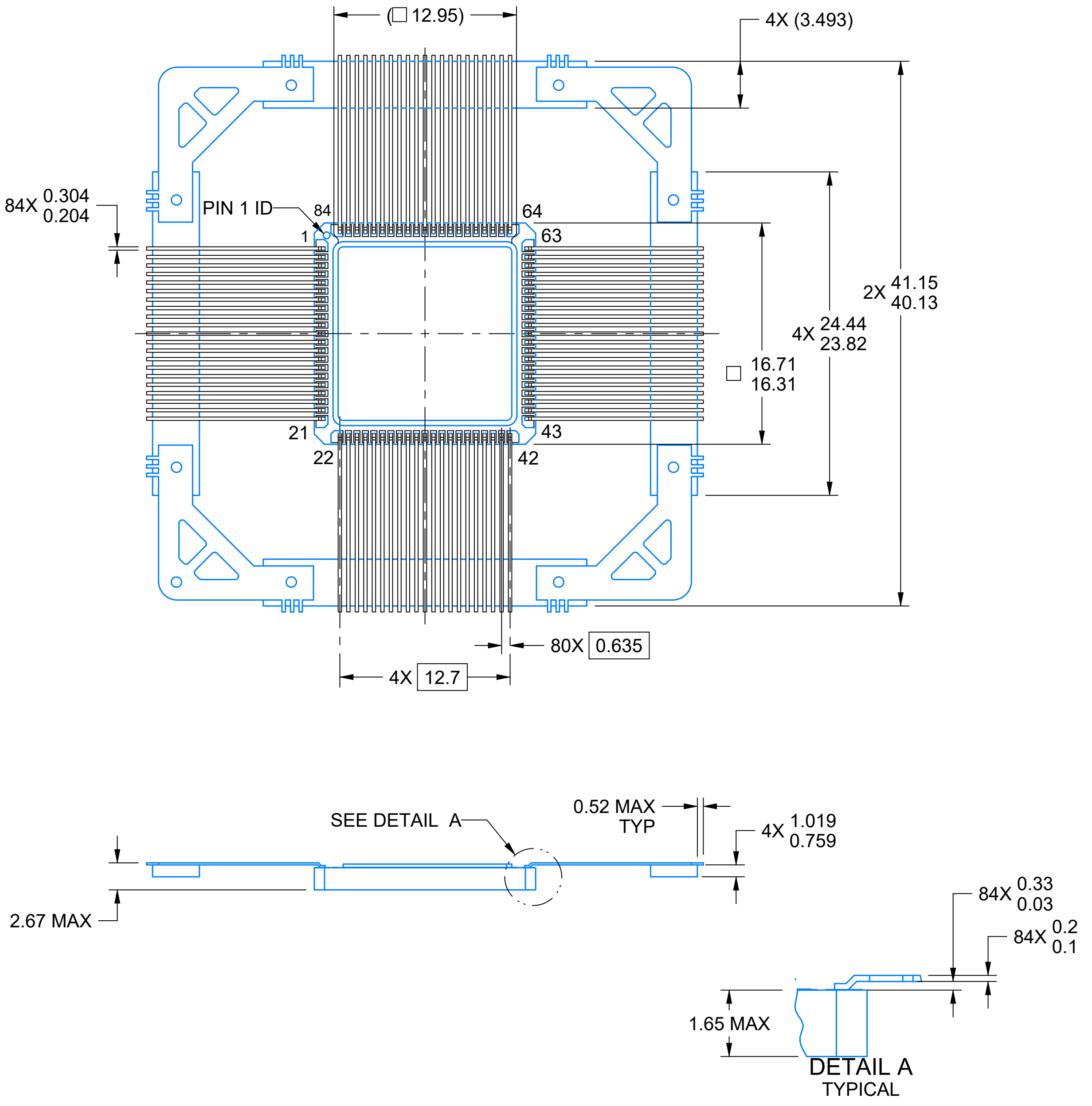
PACKAGE OUTLINE

CFP - 2.67 mm max height



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid.
4. The lid and the heat sink are connected to ground leads.
5. The leads are gold plated and can be solder dipped.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTSMAN
A	RELEASE NEW DRAWING	2213474	07/10/2025	LI JIANG / ANIS FAUZI

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